

Title (en)

TRANSPARENT CONDUCTIVE MULTILAYER ELECTRODE AND ASSOCIATED MANUFACTURING PROCESS

Title (de)

TRANSPARENTE LEITFÄHIGE MEHRSCHICHTIGE ELEKTRODE UND ENTSPRECHENDES HERSTELLUNGSVERFAHREN

Title (fr)

ELECTRODE TRANSPARENTE CONDUCTRICE MULTICOUCHE ET PROCÉDÉ DE FABRICATION ASSOCIÉ

Publication

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Application

EP 12737735 A 20120702

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Abstract (en)

[origin: WO2013004667A1] The present invention relates to a transparent conductive multilayer electrode comprising a substrate layer (1), a tie layer (2), a percolating network of metal nanowires (3), and an electrical homogenization layer (4), said electrical homogenization layer (4) comprising: an elastomer having a glass transition temperature Tg below 20oC; and/or a thermoplastic having a glass transition temperature below 20oC; and/or a polymer; a conductive, optionally substituted, polythiophene; and, conductive or semiconductor nanoscale fillers.

IPC 8 full level

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US 2011139253 A1 20110616 - WACHI AYAKO [JP], et al

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